

Pentium™ Family
User's Manual



Volume 1: Data Book

One good thing

1979 – 8086 and 8088 CPU

leads to another...



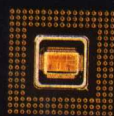
1982 – 80286 CPU

and another...



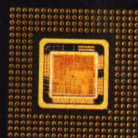
1985 – Intel386™ CPU

and another...



1989 – Intel486™ CPU

and another...



1993 – Pentium™ Processor

1994 – Pentium™ Processor
(90 & 100 MHz)



and another...and another...

奔腾™ 系列用户手册

第一卷 数据手册

(英文版)

江苏工业学院图书馆
藏书章

上海科学普及出版社

(沪)新登字第 305 号

责任编辑: 胡名正

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奔腾™系列用户手册

第一卷 数据手册

(英文版)

上海科学普及出版社出版发行

(上海曹杨路 500 号 邮政编码 200063)

上海竟成印刷厂印刷

开本 787×960 1/16 印张 39

1994 年 10 月第 1 版 1994 年 10 月第 1 次印刷

ISBN 7-5427-0930-5/TP·221 定价: 85.00 元

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